

- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Description

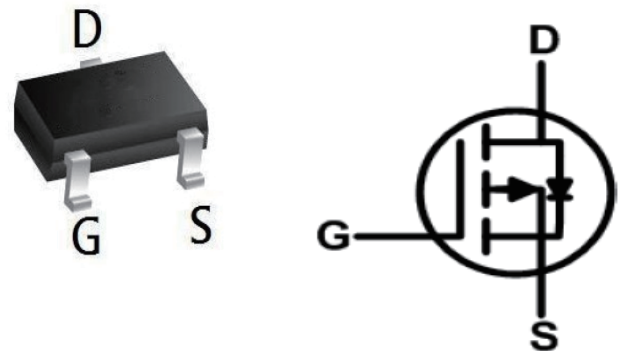
The 2319 is the high cell density trenched P-ch MOSFETs, which provides excellent $R_{DS(on)}$ and efficiency for most of the small power switching and load switch applications. The 2319 meets the RoHS and Green Product with full function reliability approved.

Product Summary

RoHS

BVDSS	$R_{DS(on)}$	I_D
-40V	63mΩ	-4A

SOT23 Pin Configurations



Absolute Maximum Ratings

Symbol	Parameter	Rating	Unit
V_{DS}	Drain-Source Voltage	-40	V
V_{GS}	Gate-Source Voltage	±20	V
I_D	Continuous Drain Current $T_A = 25^\circ\text{C}$	-4	A
I_{DM}	Pulsed Drain Current ₁	-20	A
P_D	Power Dissipation $T_A = 25^\circ\text{C}$	1.2	W
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 to 150	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Value	Unit
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient ₂	104	$^\circ\text{C/W}$

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test condition	Min.	Typ.	Max.	Units
Static Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = -250μA	-40	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = -40V, V _{GS} = 0V	-	-	-1	μA
I _{GSS}	Gate-Body Leakage	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
V _{GS(th)}	Gate-Threshold Voltage	V _{DS} = V _{GS} , I _D = -250μA	-1.2	-1.5	-2.5	V
R _{DS(on)}	Drain-Source on-Resistance ₃	V _{GS} = -10V, I _D = -5A	-	63	85	mΩ
		V _{GS} = -4.5V, I _D = -4A	-	80	125	
Dynamic Characteristics ₄						
C _{iss}	Input Capacitance	V _{GS} = 0V , V _{DS} = -20V, f=1.0MHz	-	553	-	pF
C _{oss}	Output Capacitance		-	50	-	
C _{rss}	Reverse Transfer Capacitance		-	42	-	
Switching Characteristics ₄						
Q _g	Total Gate Charge	V _{GS} = -10V, V _{DS} = -20V, I _D = -5A	-	11.8	-	nC
Q _{gs}	Gate-Source Charge		-	2.2	-	
Q _{gd}	Gate-Drain Charge		-	3	-	
t _{d(on)}	Turn-on Delay Time	V _{DS} = -20V, V _{GS} = -10V R _L = 2.5Ω, R _G = 3Ω	-	7	-	ns
t _r	Rise Time		-	6.5	-	
t _{d(off)}	Turn-off Delay Time		-	24	-	
t _f	Fall Time		-	7.8	-	
Drain-Source Body Diode Characteristics						
V _{DS}	Body Diode voltage ₃	I _S = -5A, V _{GS} =0V	-	-	-1.2	V
I _S	Continuous Source Current		-	-	-4	A

Notes:

- 1.Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)} = 150^\circ\text{C}$.
- 2.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper, The value in any given application depends on the user's specific board design.
- 3.Pulse Test: Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 4.This value is guaranteed by design hence it is not included in the production test.

Typical Electrical and Thermal Characteristics (Curves)

Figure1: Output Characteristics

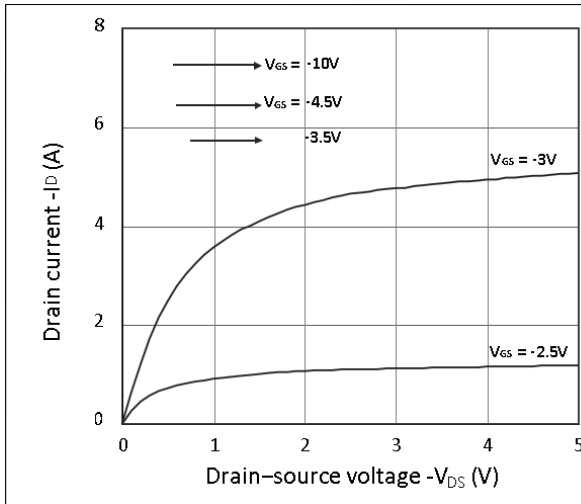


Figure 2: Typical Transfer Characteristics

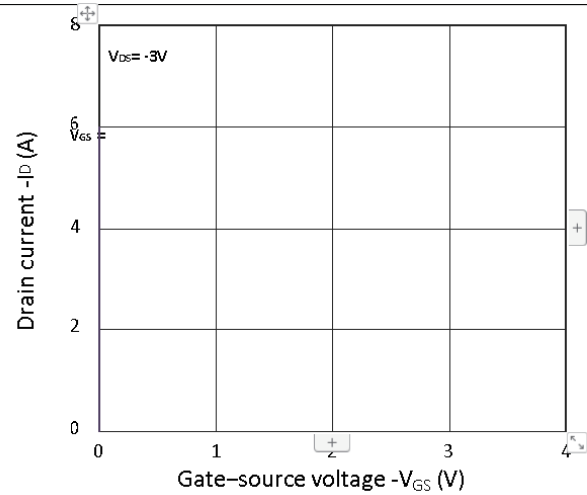


Figure 3: Forward Characteristics of Reverse

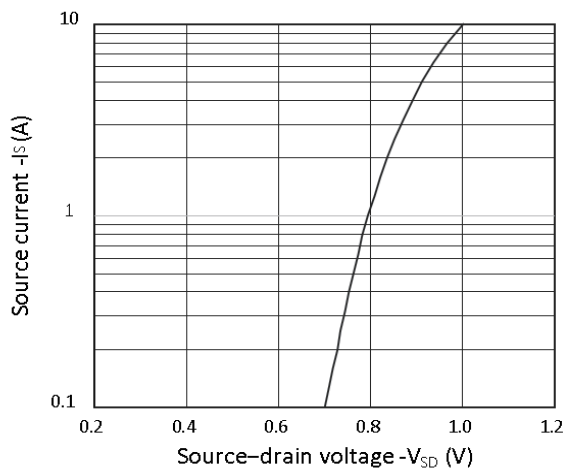


Figure 4: RDS(ON) vs. VGS

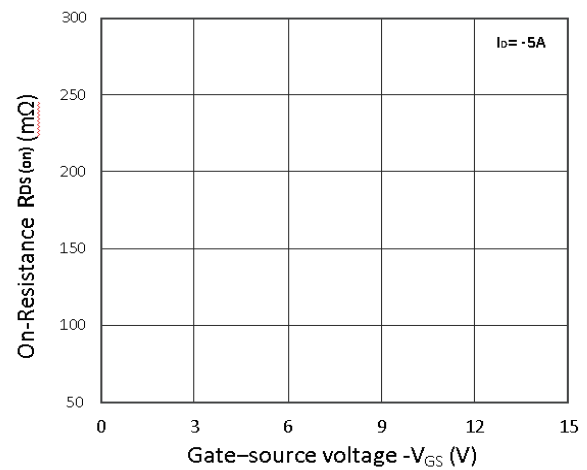


Figure 5: RDS(ON) vs. ID

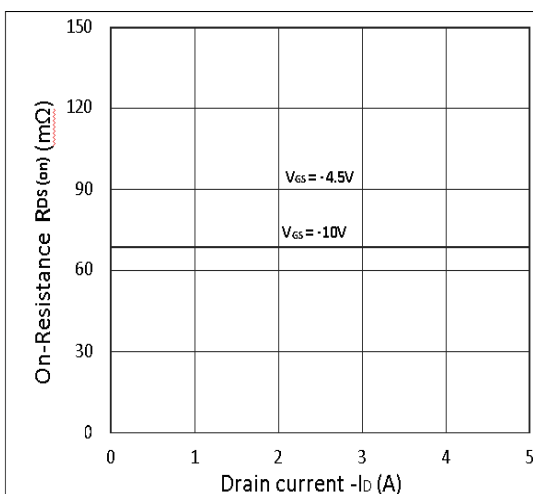
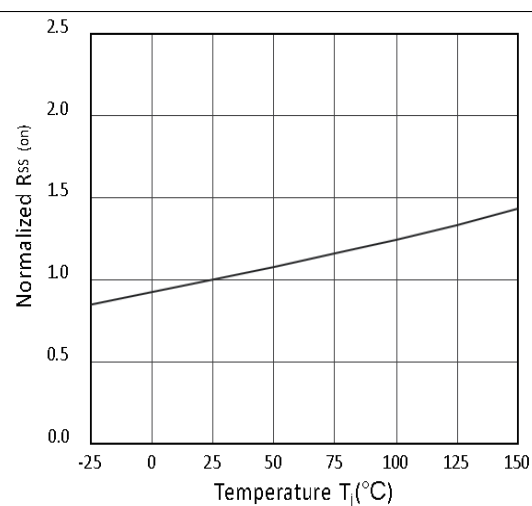


Figure 6: Normalized RDS(on) vs. Temperature



Typical Performance Characteristics

Figure 7: Capacitance Characteristics

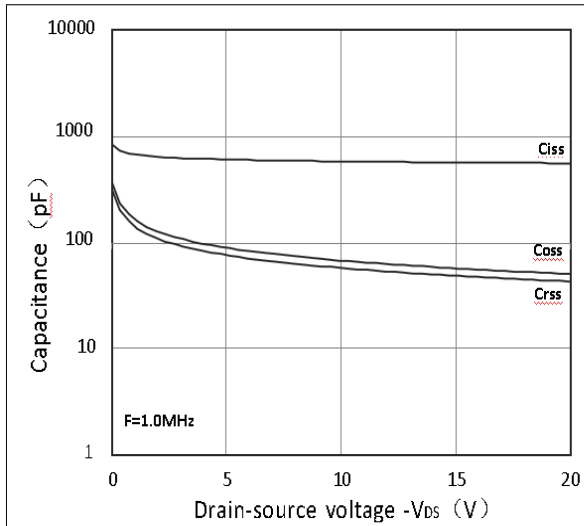
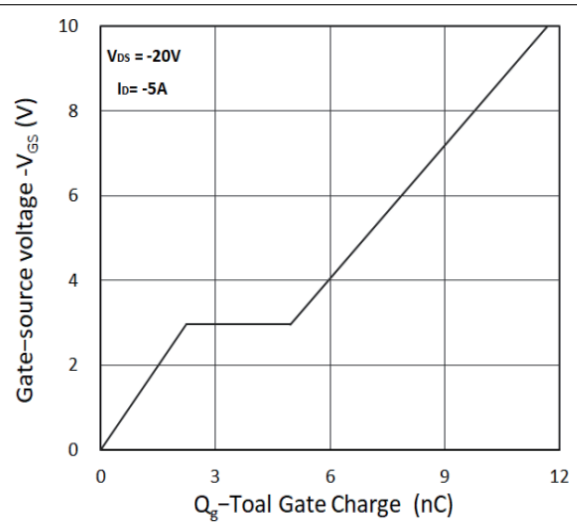
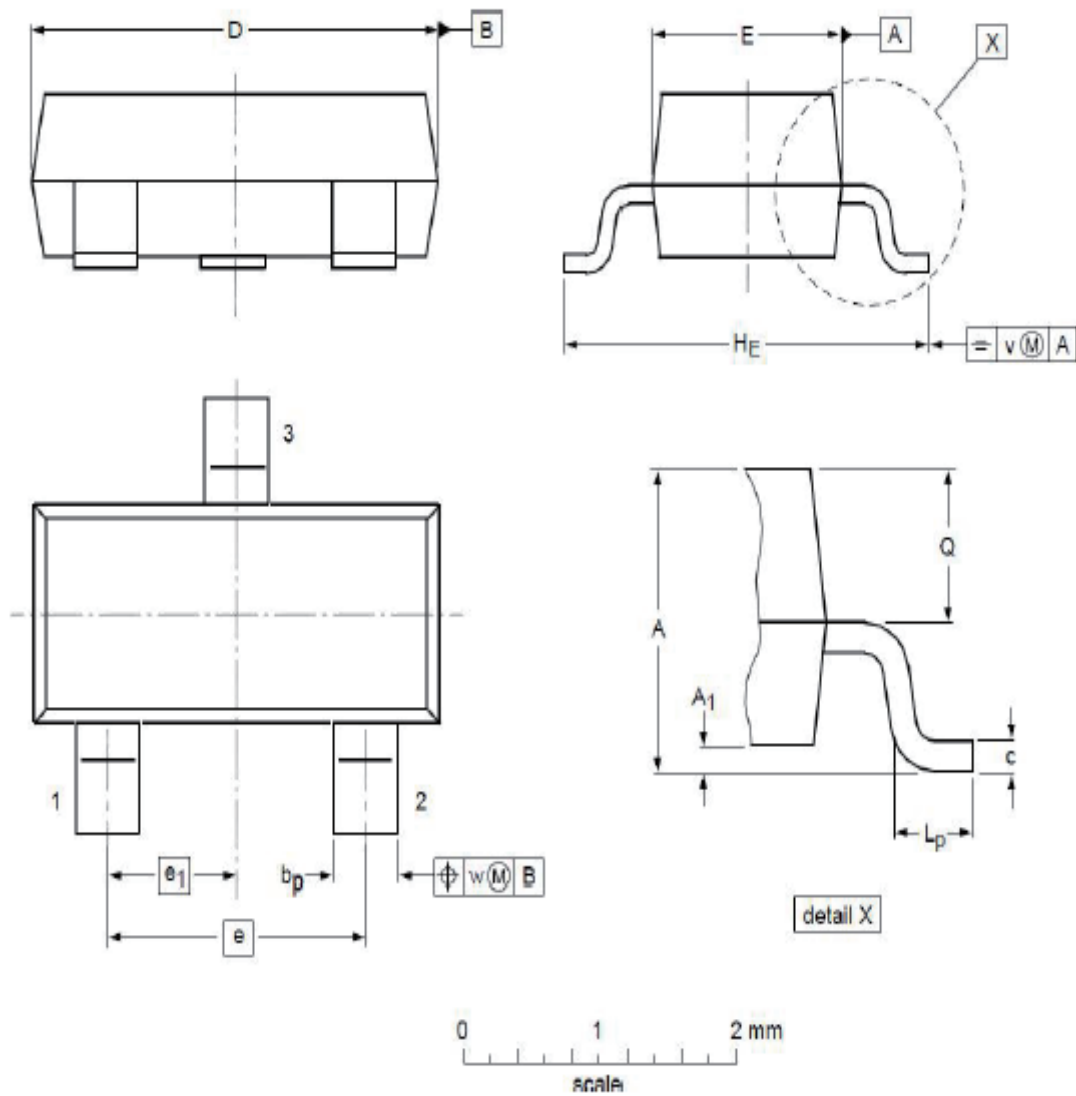


Figure 8: Gate Charge Characteristics



SOT23 Mechanical tData



DIMENSIONS (unit : mm)

Symbol	Min	Typ	Max	Symbol	Min	Typ	Max
A	0.90	1.01	1.15	A ₁	0.01	0.05	0.10
b _p	0.30	0.42	0.50	c	0.08	0.13	0.15
D	2.80	2.92	3.00	E	1.20	1.33	1.40
e	--	1.90	--	e ₁	--	0.95	--
H _E	2.25	2.40	2.55	L _p	0.30	0.42	0.50
Q	0.45	0.49	0.55	v	--	0.20	--
w	--	0.10	--				